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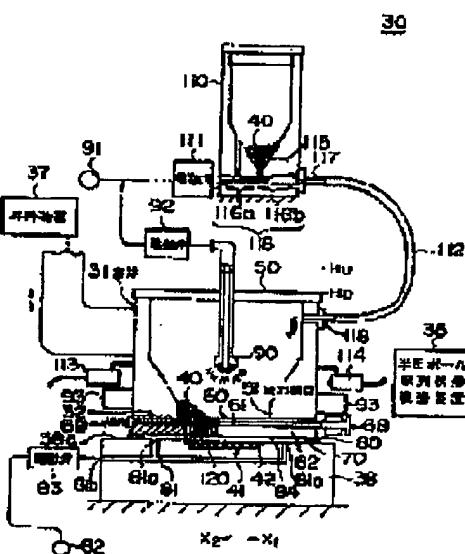
(54) METHOD AND DEVICE FOR MOUNTING SOLDER BALL

**(57) Abstract:**

**PURPOSE:** To make container inverting operations unnecessary so as to shorten the cycle time of solder ball mounting operations by supplying solder balls to pads in a state where the solder balls are arranged in correspondence to the arrangement of the pads.

**CONSTITUTION:** A container 31 contains solder balls 40 and a solder ball arranging and supplying device 32 is provided at the bottom of the container 31 and supplies the solder balls 40 to pads from the bottom of the container 31 in a state where the solder balls 40 are arranged in corresponding to the arrangement of the pads. A solder ball arranging state inspecting means 35 inspects whether or not the solder balls 40

whether or not the solder balls 40 are properly arranged. Therefore, a mounting error, the absence of a solder ball on a pad, can be prevented. A lift device 37 elevates or lowers the container 31 and device 32 against a substrate positioning table 38. The table 38 positions the substrate of an LSI package.



## **LEGAL STATUS**

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